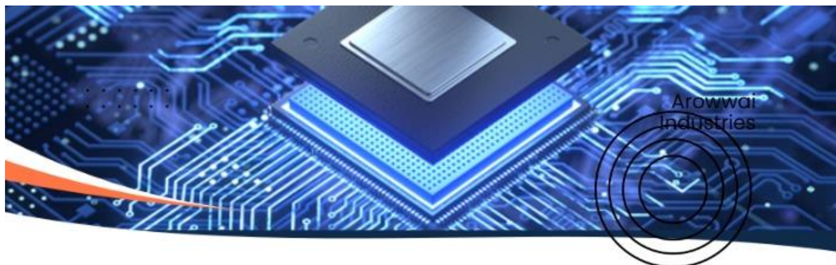
IEEE EPS Malaysia – Industry Day 2024

Oct 19th, 2024



IEEE ELECTRONICS PACKAGING SOCIETY INDUSTRY DAY 2024

Speaker 1 — Tracking the Future of Advanced Packaging: The Heterogeneous Integration Roadmap.

Mr. Paul Wesling, IEEE Fellow, IEEE EPS Distinguished Lecture

Speaker 2 — Flip Chip, Hybrid Bonding, and Wafer-Level Packaging

Dr. John Lau, Unimicron Technology, IEEE Fellow, IMAPS Fellow, ASEME Fellow

Speaker 3 — Fundamentals of electrical design for Packaging

Dr Rohit Y. Sharma, Associate Professor, Indian Institute of Technology Ropar, IEEE EPS Distinguished Lecturer

Note: Detail program are found in the registratrion form.

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- **IEEE EPS Malaysia with it's IEMT Conference 2024 committee (led by Dr Bernard Lim and Hoo Kooi) has organized IEEE EPS Industry Day 2024 on Oct 19th, from 9am to 12noon, at CEDEC University Sains Malaysia (USM). 3 IEEE EPS Distinguished Lecturers namely Mr Paul Wesling, Dr John Lau, and Dr Rohit Y. Sharma gave very good sharing on Advanced Packaging related topics, including HI roadmap, PIC and EIC co-package, and electrical design for packaging.**
- **Event was attended by about 50 participants from industry and USM. It was a great learning experience as commented by many attendees.**

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